



# Product data sheet

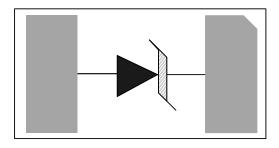
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## Schematic & PIN Configuration



DFN1006-2

#### Features

- **56**Watts peak pulse power (tp =  $8/20\mu s$ )
- Tiny DFN1006 package
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance (Cj=0.45pF typ.)
- Protection one data/power line to:
- IEC 61000-4-2 ±20kV contact ±20kV air
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 4A (8/20µs )

#### **Applications**

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation

#### **Mechanical Data**

- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

# Electrical Parameters (TA = 25 °C unless otherwise noted)

Symbol	Parameter	
Ipp	Maximum Reverse Peak Pulse Current	I <sub>F</sub>
Vc	Clamping Voltage @ IPP	
VRWM	Working Peak Reverse Voltage	
IR	Maximum Reverse Leakage Current @ VRWM	$ \underbrace{V_{C} V_{BR} V_{RWM}}_{I_{R} V_{F}} \rightarrow V $
VBR	Breakdown Voltage @ IT	
IT	Test Current	
		IPP

Note:.  $8/20\mu s$  pulse waveform.



# **Absolute Maximum Rating**

Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p = 8/20 \mu s$ )	P <sub>PP</sub>	56	Watts
Peak Pulse Current ( $t_p = 8/20\mu s$ ) (note1)	I <sub>pp</sub>	4	А
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	20 20	kV
Lead Soldering Temperature	$T_L$	260(10seconds)	°C
Junction Temperature	TJ	-55 to + 125	°C
Storage Temperature	T <sub>stg</sub>	-55 to + 125	°C

# **Electrical Characteristics**

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V <sub>RWM</sub>				5.0	v
Reverse Breakdown Voltage	$V_{BR}$	I <sub>T</sub> =1mA	6.0	7.5		V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> =5V,Т=25°С			100	nA
Peak Pulse Current	$I_{PP}$	tp =8/20µs			4	А
Clamping Voltage	V <sub>C</sub>	Ipp=4A,tp=8/20µs			14	V
Junction Capacitance	C <sub>j</sub>	$V_R = 0V, f = 1MHz$		0.45	0.6	pF





#### Typical **Characteristics**

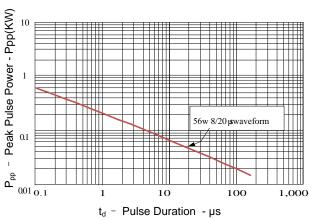


Figure 1: Peak Pulse Power vs. Pulse Time Figure 2: Power Derating Curve

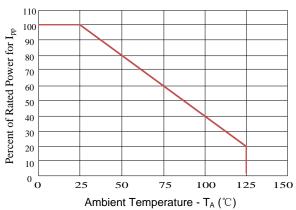


Figure3: Pulse Waveform

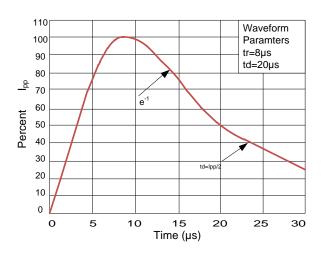
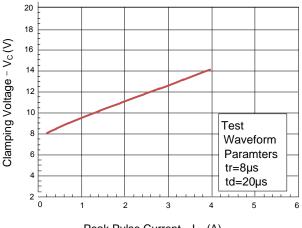


Figure 4: Clamping Voltage vs.lpp

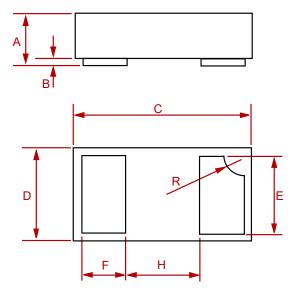


Peak Pulse Current - IPP (A)



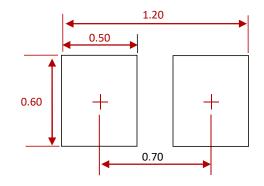
ESD5341N-MS HF Compiance

## PACKAGE MECHANICAL DATA



Dire	Inches		Millimeters		
Dim	MIN	MAX	MIN	МАХ	
A	0.0125	0.02	0.32	0.52	
В	0.000	0.002	0.00	0.05	
С	0.037	0.043	0.95	1.080	
D	0.022	0.027	0.55	0.680	
E	0.016	0.024	0.40	0.60	
F	0.008	0.012	0.20	0.30	
н	0.015Typ.		0.40Тур.		
R	0.001	0.005	0.05	0.15	

# Suggested Pad Layout



NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
  - CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
ESD5341N-MS	DFN1006-2	10000



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